XP-002236300

AN - 2000-199443 [18]
AP - JP19980151106 19980601
CPY - FUIT
DC - A85 G03 L03 U11 V04
FS - CPI;EPI
IC - C09J4/00 ; C09J161/06 ; C09J161/24 ; C09J161/28 ; C09J163/00 ; C09J201/00 ; H01L21/60 ; H05K3/34
MC - A11-C01C A11-C02 A12-E07 G03-B04 L03-H04E6 L04-C17D - U11-E01 V04-R04A
PA - (FUIT) FUJITSU LTD
PN - JP11343465 A 19991214 DW200018 C09J4/00 007pp
PR - JP19980151106 19980601
XA - C2000-061545
XIC - C09J-004/00 ; C09J-161/06 ; C09J-161/24 ; C09J-161/28 ; C09J-163/00 ; C09J-201/00 ; H01L-021/60 ; H05K-003/34
XP - N2000-148253
AB - JP11343465 NOVELTY - Adhesive containing polymerization initiator, reducing agent and activator containing monomer or oligomer is separated into two types of adhesive (3a,3b) such that initiator, reducing agent and activator does not coexist. Electronic component (1) is bonded to a substrate (2) using two types of adhesive by polymerization hardening of monomer or oligomer at normal temperature.
- DETAILED DESCRIPTION - The adhesive containing polymerization initiator, reducing agent (which decomposes the initiator) and activator containing monomer or oligomer which carries out polymerization by active radical generated by decomposition of initiator, is divided into two types of adhesive so that the initiator, reducing agent and activator does not coexist simultaneously. The electronic component is bonded to the substrate using two types of adhesive so that the initiator, reducing agent and activator coexists and polymerization hardening of monomer or oligomer is carried out at normal temperature. An INDEPENDENT CLAIM is also included for adhesion of electronic component on the substrate.
- USE - For mounting semiconductor devices such as integrated circuit and large scale integrated circuit on the substrate.
- ADVANTAGE - The electronic component and substrate is connected economically at normal temperature, using the adhesive . The generation of thermal stress in electronic component and substrate is prevented. Therefore, the junction part of substrate is not deformed even when it is made of soft material.
- DESCRIPTION OF DRAWING - The figure illustrates the method for connecting electronic component to the substrate. (1) Electronic Component; ; (2) Substrate; ; (3a,3b) Two types of adhesive.
- (Dwg.1/1)
IW - ADHESIVE MOUNT ELECTRONIC COMPONENT SEMICONDUCTOR DEVICE SUBSTRATE MOUNT ELECTRONIC COMPONENT SUBSTRATE ADHESIVE HARDEN OLIGOMER MONOMER CONTAIN ADHESIVE NORMAL TEMPERATURE
IKW - ADHESIVE MOUNT ELECTRONIC COMPONENT SEMICONDUCTOR DEVICE SUBSTRATE MOUNT ELECTRONIC COMPONENT SUBSTRATE ADHESIVE HARDEN OLIGOMER MONOMER CONTAIN ADHESIVE NORMAL TEMPERATURE
NC - 001

OPD - 1998-06-01
ORD - 1999-12-14
PAW - (FUIT) FUJITSU LTD
TI - Adhesive used for mounting electronic component such as semiconductor device on substrate - involves mounting the electronic component on substrate using adhesive by polymerization hardening of oligomer or monomer contained in adhesive, at normal temperature
A01 - [001] 018 ; H0328 ; M9999 M2073 ; L9999 L2391 ; L9999 L2073 ; K9370 ; P0464-R D01 D22 D42 F47
- [002] 018 ; H0328 ; M9999 M2073 ; L9999 L2391 ; L9999 L2073 ; K9370 ; P0226 P0282-R D01 D18 F30
- [003] 018 ; R00123 G1821 D01 D50 D81 F78 ; H0328 ; M9999 M2073 ; L9999 L2391 ; L9999 L2073 ; K9370 ; H0011-R ; P0259-R P0226 D01
- [004] 018 ; R00859 G1809 G1649 D01 D23 D22 D31 D45 D50 D76 D83 F19 F10 F07 ; H0328 ; M9999 M2073 ; L9999 L2391 ; L9999 L2073 ; K9370 ; H0011-R ; P0259-R P0226 D01
- [005] 018 ; ND01 ; ND04 ; Q9999 Q6644-R ; Q9999 Q6688 Q6644 ; Q9999 Q7330-R ; Q9999 Q7476 Q7330 ; B9999 B3838-R B3747
- [006] 018 ; D01 D26 D11 D10 D51-R D58 ; R00474 D01 D11 D10 D19 D18 D31 D50 D76 D89 F48 ; R00610 D01 D19 D18 D32 D50 D63 D76 D93 F42 ; R01732 D00 F48 H- O- 6A ; R01536 D01 D11 D10 D23 D22 D31 D46 D50 D75 D88 F34 F48 ; R01412 D01 D11 D10 D19 D18 D31 D50 D63 D76 D91 F42 ; A999 A157-R ; A999 A771
- [007] 018 ; Fe 8B Tr ; R01020 G1650 G1649 D01 D11 D10 D19 D18 D31 D50 D76 D88 F08 F07 ; R01013 D01 D11 D10 D50 D86 F08 F07 ; R00643 D01 D23 D22 D31 D45 D50 D75 D83 F68 ; R13049 D01 D11 D10 D50 D84 F15 F76 F92 ; R07251 D01 D11 D10 D14 D13 D31 D50 D61 D75 F36 F35 Co 8B Tr ; R05368 D01 D11 D10 D50 D92 F08 F07 ; D01 D11 D10 D50 D84 F22 ; D01 D11 D10 D50 D82 F68 ; D01 D11 D10 D50 D61-R D94 F23 Ti 4B Tr ; A999 A146
- [008] 018 ; D00 ; A999 A237
- [009] 018 ; R05319 D00 D09 Ag ; A999 A135 ; S9999 S1456-R
A02 - [001] 018 ; P0000 ; A999 A782 ; A999 A135
- [002] 018 ; K9552 K9483 ; K9687 K9676 ; K9712 K9676 ; B9999 B3270 B3190 ; Q9999 Q7114-R